## Optocoupler, Phototransistor Output, with Base Connection


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## DESCRIPTION

This data sheet presents five families of Vishay industry standard single channel phototransistor couplers. These families include the 4N35, 4N36, 4N37, 4N38 couplers.
Each optocoupler consists of gallium arsenide infrared LED and a silicon NPN phototransistor.
These couplers are Underwriters Laboratories (UL) listed to comply with a $5300 \mathrm{~V}_{\text {RMS }}$ isolation test voltage.
This isolation performance is accomplished through Vishay double molding isolation manufacturing process. Comliance to DIN EN 60747-5-5 partial discharge isolation specification is available for these families by ordering option 1.
These isolation processes and the Vishay ISO9001 quality program results in the highest isolation performance available for a commecial plastic phototransistor optocoupler.
The devices are available in lead formed configuration suitable for surface mounting and are available either on tape and reel, or in standard tube shipping containers.
Note:
For additional design information see application note 45 normalized curves

## FEATURES

- Isolation test voltage $5300 \mathrm{~V}_{\mathrm{RMS}}$
- Interfaces with common logic families
- Input-output coupling capacitance $<0.5 \mathrm{pF}$
- Industry standard dual-in-line 6 pin package
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC


## APPLICATIONS

- AC mains detection
- Reed relay driving
- Switch mode power supply feedback
- Telephone ring detection
- Logic ground isolation
- Logic coupling with high frequency noise rejection


## AGENCY APPROVALS

- Underwriters laboratory file no. E52744
- DIN EN 60747-5-5 (VDE 0884) available with option 1


## ORDER INFORMATION

| PART | REMARKS |
| :---: | :---: |
| 4N35-X000 | CTR > $100 \%$, DIP-6 |
| 4N36-X000 | CTR > $100 \%$, DIP-6 |
| 4N37-X000 | CTR > $100 \%$, DIP-6 |
| 4N38 | CTR > 20 \%, DIP-6 |
| 4N35-X006 | CTR > $100 \%$, DIP-6 400 mil (option 6) |
| 4N35-X007 | CTR > $100 \%$, SMD-6 (option 7) |
| 4N35-X009 | CTR > $100 \%$, SMD-6 (option 9) |
| 4N36-X007 | CTR > $100 \%$, SMD-6 (option 7) |
| 4N36-X009 | CTR > $100 \%$, SMD-6 (option 9) |
| 4N37-X006 | CTR > $100 \%$, DIP-6 400 mil (option 6) |
| 4N38-X009 | CTR > 100 \%, SMD-6 (option 9) |

## Note

For additional information on the available options refer to option information.

## Vishay Semiconductors Optocoupler, Phototransistor Output, with Base Connection

| ABSOLUTE MAXIMUM RATINGS (1) |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| INPUT |  |  |  |  |
| Reverse voltage |  | $\mathrm{V}_{\text {R }}$ | 6 | V |
| Forward current |  | $\mathrm{I}_{\mathrm{F}}$ | 60 | mA |
| Surge current | $\mathrm{t} \leq 10 \mu \mathrm{~s}$ | $\mathrm{I}_{\text {FSM }}$ | 2.5 | A |
| Power dissipation |  | $\mathrm{P}_{\text {diss }}$ | 100 | mW |
| OUTPUT |  |  |  |  |
| Collector emitter breakdown voltage |  | $\mathrm{V}_{\text {CEO }}$ | 70 | V |
| Emitter base breakdown voltage |  | $\mathrm{V}_{\text {EBO }}$ | 7 | V |
| Collector current |  | $\mathrm{I}_{\mathrm{c}}$ | 50 | mA |
|  | $\mathrm{t} \leq 1 \mathrm{~ms}$ | $\mathrm{I}_{\mathrm{C}}$ | 100 | mA |
| Power dissipation |  | $\mathrm{P}_{\text {diss }}$ | 150 | mW |
| COUPLER |  |  |  |  |
| Isolation test voltage |  | $\mathrm{V}_{\text {ISO }}$ | 5300 | $\mathrm{V}_{\text {RMS }}$ |
| Creepage |  |  | $\geq 7$ | mm |
| Clearance |  |  | $\geq 7$ | mm |
| Isolation thickness between emitter and detector |  |  | $\geq 0.4$ | mm |
| Comparative tracking index | DIN IEC 112/VDE 0303, part 1 |  | 175 |  |
| Isolation resistance | $\mathrm{V}_{10}=500 \mathrm{~V}, \mathrm{~T}_{\text {amb }}=25^{\circ} \mathrm{C}$ | $\mathrm{R}_{10}$ | $10^{12}$ | $\Omega$ |
|  | $\mathrm{V}_{\text {IO }}=500 \mathrm{~V}, \mathrm{~T}_{\mathrm{amb}}=100^{\circ} \mathrm{C}$ | $\mathrm{R}_{10}$ | $10^{11}$ | $\Omega$ |
| Storage temperature |  | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Operating temperature |  | $\mathrm{T}_{\text {amb }}$ | - 55 to + 100 | ${ }^{\circ} \mathrm{C}$ |
| Junction temperature |  | $\mathrm{T}_{\mathrm{j}}$ | 100 | ${ }^{\circ} \mathrm{C}$ |
| Soldering temperature ${ }^{(2)}$ | max. 10 s dip soldering: distance to seating plane $\geq 1.5 \mathrm{~mm}$ | $\mathrm{T}_{\text {sld }}$ | 260 | ${ }^{\circ} \mathrm{C}$ |

## Notes

(1) $\mathrm{T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.
(2) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering condditions for through hole devices (DIP).

| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| INPUT |  |  |  |  |  |  |  |
| Junction capacitance | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ |  | $\mathrm{C}_{\mathrm{j}}$ |  | 50 |  | pF |
| Forward voltage ${ }^{(2)}$ | $\mathrm{I}_{\mathrm{F}}=10 \mathrm{~mA}$ |  | $\mathrm{V}_{\mathrm{F}}$ |  | 1.3 | 1.5 | V |
|  | $\mathrm{I}_{\mathrm{F}}=10 \mathrm{~mA}, \mathrm{~T}_{\mathrm{amb}}=-5 \mathrm{c}^{\circ} \mathrm{C}$ |  | $\mathrm{V}_{\mathrm{F}}$ | 0.9 | 1.3 | 1.7 | V |
| Reverse current ${ }^{(2)}$ | $\mathrm{V}_{\mathrm{R}}=6 \mathrm{~V}$ |  | $\mathrm{I}_{\mathrm{R}}$ |  | 0.1 | 10 | $\mu \mathrm{A}$ |
| Capacitance | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ |  | $\mathrm{C}_{0}$ |  | 25 |  | pF |
| OUTPUT |  |  |  |  |  |  |  |
| Collector emitter breakdown voltage (2) | $\mathrm{I}_{\mathrm{C}}=1 \mathrm{~mA}$ | 4N35 | $\mathrm{BV}_{\text {CEO }}$ | 30 |  |  | V |
|  |  | 4N36 | $\mathrm{BV}_{\text {CEO }}$ | 30 |  |  | V |
|  |  | 4N37 | $\mathrm{BV}_{\text {CEO }}$ | 30 |  |  | V |
|  |  | 4N38 | $\mathrm{BV}_{\text {CEO }}$ | 80 |  |  | V |
| Emitter collector breakdown voltage ${ }^{(2)}$ | $\mathrm{I}_{\mathrm{E}}=100 \mu \mathrm{~A}$ |  | $B V_{\text {ECO }}$ | 7 |  |  | V |

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| ELECTRICAL CHARACTERISTICS (1) |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| OUTPUT |  |  |  |  |  |  |  |
| Collector base breakdown voltage ${ }^{(2)}$ | $\mathrm{I}_{\mathrm{C}}=100 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=1 \mu \mathrm{~A}$ | 4N35 | $\mathrm{BV}_{\text {CBO }}$ | 70 |  |  | V |
|  |  | 4N36 | $\mathrm{BV}_{\text {CBO }}$ | 70 |  |  | V |
|  |  | 4N37 | $B V_{\text {CBO }}$ | 70 |  |  | V |
|  |  | 4N38 | $\mathrm{BV}_{\text {CBO }}$ | 80 |  |  | V |
| Collector emitter leakage current ${ }^{(2)}$ | $\mathrm{V}_{\text {CE }}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=0$ | 4N35 | $\mathrm{I}_{\text {CEO }}$ |  | 5 | 50 | nA |
|  |  | 4N36 | $\mathrm{I}_{\text {CEO }}$ |  | 5 | 50 | nA |
|  | $\mathrm{V}_{\text {CE }}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=0$ | 4N37 | $\mathrm{I}_{\text {ceo }}$ |  | 5 | 50 | nA |
|  | $\mathrm{V}_{\mathrm{CE}}=60 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=0$ | 4N38 | $\mathrm{I}_{\text {CEO }}$ |  |  | 50 | nA |
|  | $\begin{gathered} V_{C E}=30 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=0, \\ T_{\mathrm{amb}}=100^{\circ} \mathrm{C} \end{gathered}$ | 4N35 | $\mathrm{I}_{\text {ceo }}$ |  |  | 500 | $\mu \mathrm{A}$ |
|  |  | 4N36 | $\mathrm{I}_{\text {CEO }}$ |  |  | 500 | $\mu \mathrm{A}$ |
|  |  | 4N37 | $\mathrm{I}_{\text {CEO }}$ |  |  | 500 | $\mu \mathrm{A}$ |
|  | $\begin{gathered} \mathrm{V}_{\mathrm{CE}}=60 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=0, \\ \mathrm{~T}_{\mathrm{amb}}=100^{\circ} \mathrm{C} \\ \hline \end{gathered}$ | 4N38 | $I_{\text {cee }}$ |  | 6 |  | $\mu \mathrm{A}$ |
| Collector emitter capacitance | $\mathrm{V}_{\mathrm{CE}}=0$ |  | $\mathrm{C}_{\text {CE }}$ |  | 6 |  | pF |
| COUPLER |  |  |  |  |  |  |  |
| Resistance, input output ${ }^{(2)}$ | $\mathrm{V}_{10}=500 \mathrm{~V}$ |  | $\mathrm{R}_{10}$ | $10^{11}$ |  |  | $\Omega$ |
| Capacitance, input output | $\mathrm{f}=1 \mathrm{MHz}$ |  | $\mathrm{C}_{10}$ |  | 0.5 |  | pF |

## Notes

(1) $\mathrm{T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$, unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.
(2) Indicates JEDEC registered value.

## CURRENT TRANSFER RATIO

| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN | TYP. | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DC current transfer ratio ${ }^{(1)}$ | $\mathrm{V}_{\mathrm{CE}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=10 \mathrm{~mA}$ | 4N35 | CTR ${ }_{\text {DC }}$ | 100 |  |  | \% |
|  |  | 4N36 | CTR ${ }_{\text {DC }}$ | 100 |  |  | \% |
|  |  | 4N37 | CTR ${ }_{\text {DC }}$ | 100 |  |  | \% |
|  | $\mathrm{V}_{\mathrm{CE}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | 4N38 | CTR ${ }_{\text {DC }}$ | 20 |  |  | \% |
|  | $\begin{aligned} & \mathrm{V}_{\mathrm{CE}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{F}}=10 \mathrm{~mA}, \\ & \mathrm{~T}_{\mathrm{A}}=-55^{\circ} \mathrm{C} \text { to }+100^{\circ} \mathrm{C} \end{aligned}$ | 4N35 | CTR ${ }_{\text {DC }}$ | 40 | 50 |  | \% |
|  |  | 4N36 | CTR ${ }_{\text {DC }}$ | 40 | 50 |  | \% |
|  |  | 4N37 | CTR ${ }_{\text {DC }}$ | 40 | 50 |  | \% |
|  |  | 4N38 | CTR ${ }_{\text {DC }}$ |  | 30 |  | \% |

## Note

${ }^{(1)}$ Indicates JEDEC registered values.
SWITCHING CHARACTERISTICS

|  |  |  |  |  |  |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Switching time ${ }^{(1)}$ | $\mathrm{V}_{\mathrm{CC}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=2 \mathrm{~mA}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ | $\mathrm{t}_{\mathrm{on}}, \mathrm{t}_{\mathrm{off}}$ |  | 10 |  | $\mu \mathrm{~s}$ |

## Note

${ }^{(1)}$ Indicates JEDEC registered values.

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## TYPICAL CHARACTERISTICS

$\mathrm{T}_{\text {amb }}=25^{\circ} \mathrm{C}$, unless otherwise specied


Fig. 1 - Forward Voltage vs. Forward Current


Fig. 2 - Normalized Non-Saturated and Saturated CTR vs. LED Current


Fig. 3 - Normalized Non-Saturated and Saturated CTR vs. LED Current


Fig. 4 - Normalized Non-Saturated and Saturated CTR vs. LED Current


Fig. 5 - Normalized Non-Saturated and Saturated CTR vs. LED Current


Fig. 6 - Collector Emitter Current vs. Temperature and LED Current

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Fig. 7 - Collector Emitter Leakage Current vs. Temperature


Fig. 8 - Normalized CTR ${ }_{c b}$ vs. LED Current and Temperature


Fig. 9 - Normalized Photocurrent vs. $\mathrm{I}_{\mathrm{F}}$ and Temperature


Fig. 10 - Normalized Non-Saturated $\mathrm{h}_{\text {FE }}$ vs. Base Current and Temperature


Fig. 11 - Normalized $h_{\text {FE }}$ vs. Base Current and Temperature


Fig. 12 - Propagation Delay vs. Collector Load Resistor

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i4n25_13

i4n25_14
Fig. 14 - Switching Schematic

PACKAGE DIMENSIONS in millimeters


ISO method A


Option 6


Option 7


Option 9


## PACKAGE MARKING



## Disclaimer

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